1 Japan Fine Ceramics (JFC)

## Company Profile

<table>
<thead>
<tr>
<th>Company Profile</th>
<th>Company Feature</th>
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<tbody>
<tr>
<td><strong>Company Name</strong></td>
<td>Japan Fine Ceramics Co., LTD.</td>
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<tr>
<td><strong>Location</strong></td>
<td>Sendai, Miyagi, JAPAN</td>
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<tr>
<td><strong>Established</strong></td>
<td>April 5, 1984</td>
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<tr>
<td><strong>Capital</strong></td>
<td>300 Million Yen</td>
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<tr>
<td><strong>Net Sales (FY ended 3/30/2019)</strong></td>
<td>8,800 Million Yen</td>
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<tr>
<td><strong>Number of Employees</strong></td>
<td>460</td>
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### Material
- **In-house material**
  - Al2O3(99.9%, 99.5%), Zirconia
- **Outsourcing material**
  - AlN(170/200/230W/m·K), Quartz, Black Alumina etc.

### Technologies
- High precise fine patterning (L/S=20µm/15µm)
- Side Pattern
- Thin film resistor
- Step fabrication
- Grooves
- Via (Cu Filled, Through Via, Castellation)

### Products
- EML, PD, MPD Carrier
- RF bridge/RF Launcher
- Optical Bench/Board
Characteristics of discrete semiconductor devices are often undermined due to the heat that is generated from inside module. To solve this, mounted substrates require heat dissipation, electric insulation and CTE which matches semiconductor chips.